NEC

MOS FIELD EFFECT TRANSISTOR
2SK3060

SWITCHING
N-CHANNEL POWER MOS FET
INDUSTRIAL USE

DESCRIPTION

The 2SK3060 is N-Channel MOS Field Effect Transistor designed for high current switching applications.

FEATURES

- Low on-state resistance
  $R_{DS(on)1}$ = 13 mΩ MAX. (V_{GS} = 10 V, I_D = 35 A)
  $R_{DS(on)2}$ = 20 mΩ MAX. (V_{GS} = 4.0 V, I_D = 35 A)
- Low C_{iss}: C_{iss} = 2400 pF TYP.
- Built-in gate protection diode

ORDERING INFORMATION

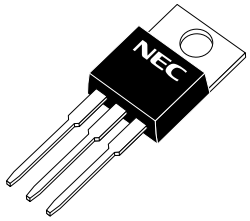
PART NUMBER	PACKAGE
2SK3060	TO-220AB
2SK3060-S	TO-262
2SK3060-ZJ	TO-263
2SK3060-Z	TO-220SMD[Note]

Note This package is produced only in Japan.

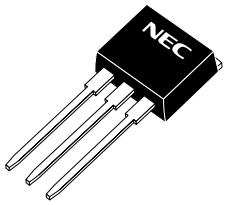
ABSOLUTE MAXIMUM RATINGS (T_A = 25 °C)

Drain to Source Voltage (V_{GS} = 0 V)	V_{DSS}	60	V
Gate to Source Voltage (V_{DS} = 0 V)	$V_{GSS(AC)}$	±20	V
Gate to Source Voltage (V_{DS} = 0 V)	$V_{GSS(DC)}$	+20, –10	V
Drain Current (DC)	$I_{D(DC)}$	±70	A
Drain Current (Pulse) [Note1]	$I_{D(pulse)}$	±210	A
Total Power Dissipation (T_C = 25°C)	P_T	70	W
Total Power Dissipation (T_A = 25°C)	P_T	1.5	W
Channel Temperature	T_{ch}	150	°C
Storage Temperature	T_{stg}	–55 to +150	°C
Single Avalanche Current [Note2]	I_{AS}	35	A
Single Avalanche Energy [Note2]	E_{AS}	122.5	mJ

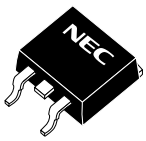
(TO-220AB)



(TO-262)



(TO-263, TO-220SMD)



Notes 1. PW ≤ 10 μs, Duty cycle ≤ 1%

★ **2.** Starting T_{ch} = 25°C, V_{DD} = 30 V, R_G = 25 Ω, V_{GS} = 20 V → 0 V

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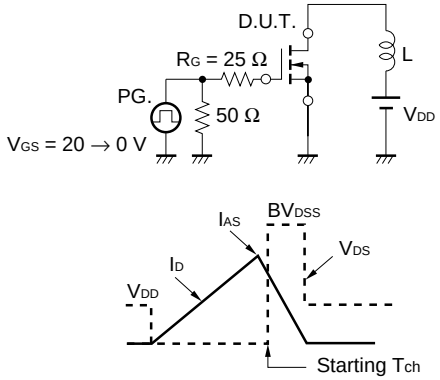
The mark ★ shows major revised points.

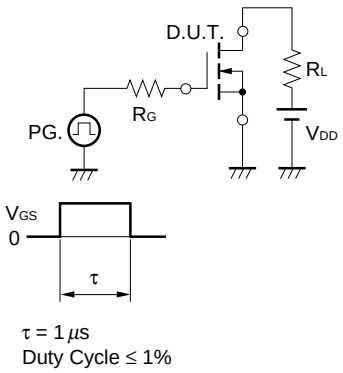
ELECTRICAL CHARACTERISTICS (T_A = 25°C)

CHARACTERISTICS	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNIT
Drain to Source On-state Resistance	$R_{DS(on)1}$	V_{GS} = 10 V, I_D = 35 A		11	13	mΩ
	$R_{DS(on)2}$	V_{GS} = 4.0 V, I_D = 35 A		16	20	mΩ
Gate to Source Cut-off Voltage	$V_{GS(off)}$	V_{DS} = 10 V, I_D = 1 mA	1.0	1.5	2.0	V
Forward Transfer Admittance	$\|y_{fs}\|$	V_{DS} = 10 V, I_D = 35 A	15	50		S
Drain Leakage Current	I_{DSS}	V_{DS} = 60 V, V_{GS} = 0 V			10	μA
Gate to Source Leakage Current	I_{GSS}	V_{GS} = ±20 V, V_{DS} = 0 V			±10	μA
Input Capacitance	C_{iss}	V_{DS} = 10 V V_{GS} = 0 V f = 1 MHz		2400		pF
Output Capacitance	C_{oss}			700		pF
Reverse Transfer Capacitance	C_{rss}			280		pF
Turn-on Delay Time	$t_{d(on)}$	I_D = 35 A V_{GS} = 10 V V_{DD} = 30 V R_G = 10 Ω		30		ns
Rise Time	t_r			600		ns
Turn-off Delay Time	$t_{d(off)}$			140		ns
Fall Time	t_f			450		ns
Total Gate Charge	Q_G	I_D = 70 A V_{DD} = 48 V V_{GS} = 10 V		50		nC
Gate to Source Charge	Q_{GS}			7.5		nC
Gate to Drain Charge	Q_{GD}			18		nC
Body Diode Forward Voltage	$V_{F(S-D)}$	I_F = 70 A, V_{GS} = 0 V		1.0		V
Reverse Recovery Time	t_{rr}	I_F = 70 A, V_{GS} = 0 V di/dt = 100 A/μs		55		ns
Reverse Recovery Charge	Q_{rr}			75		nC

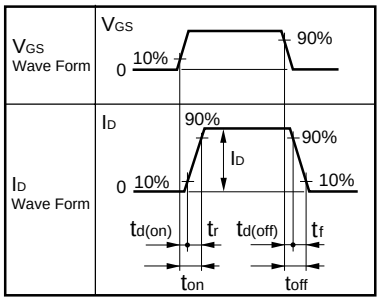
TEST CIRCUIT 1 AVALANCHE CAPABILITY



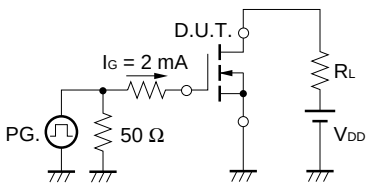
★ TEST CIRCUIT 2 SWITCHING TIME



τ = 1 μs
Duty Cycle ≤ 1%

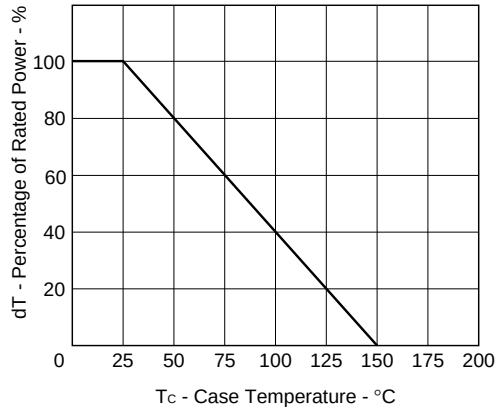


TEST CIRCUIT 3 GATE CHARGE

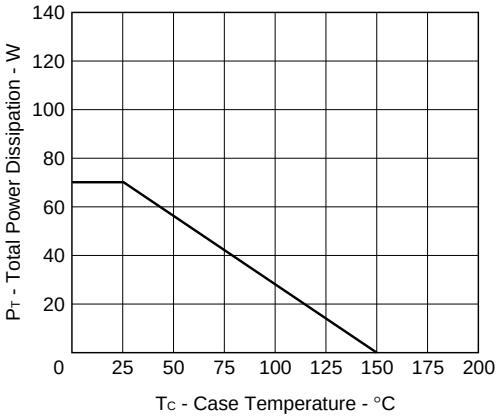


TYPICAL CHARACTERISTICS (T_A = 25°C)

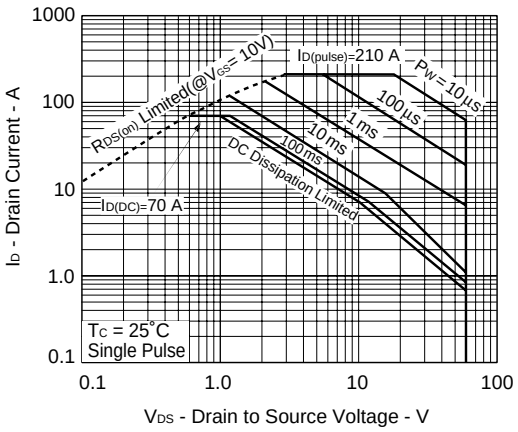
DERATING FACTOR OF FORWARD BIAS SAFE OPERATING AREA



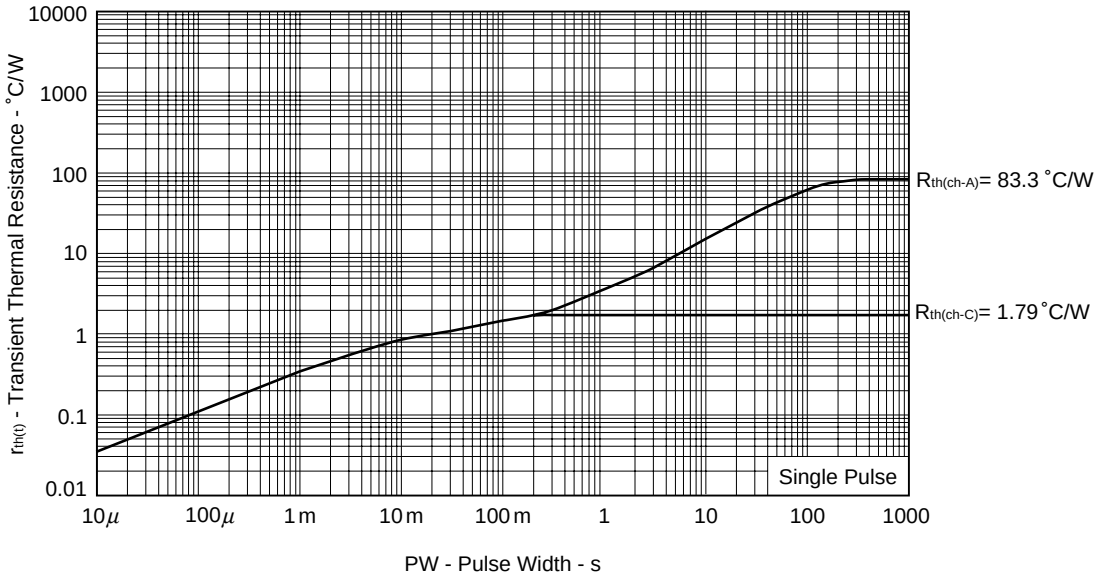
TOTAL POWER DISSIPATION vs. CASE TEMPERATURE



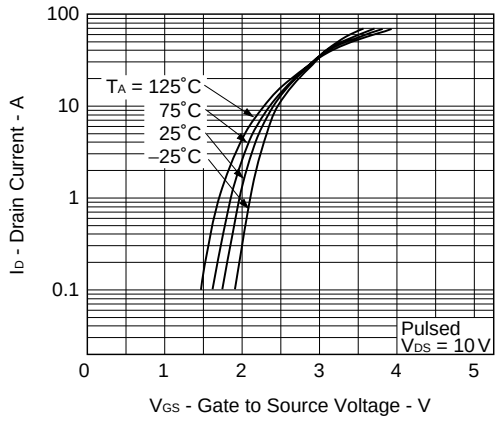
★ FORWARD BIAS SAFE OPERATING AREA



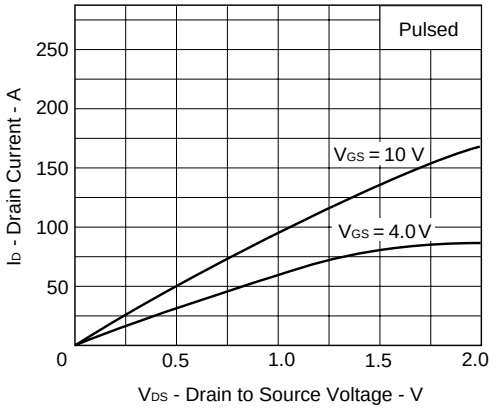
TRANSIENT THERMAL RESISTANCE vs. PULSE WIDTH



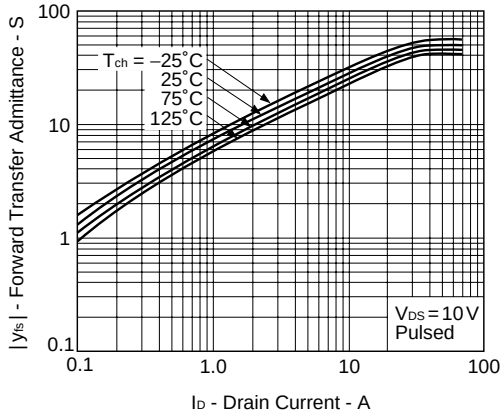
FORWARD TRANSFER CHARACTERISTICS



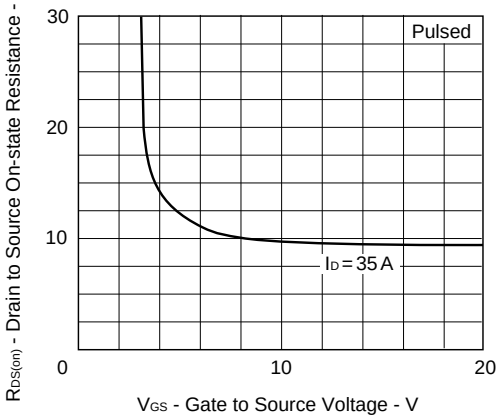
DRAIN CURRENT vs.
DRAIN TO SOURCE VOLTAGE



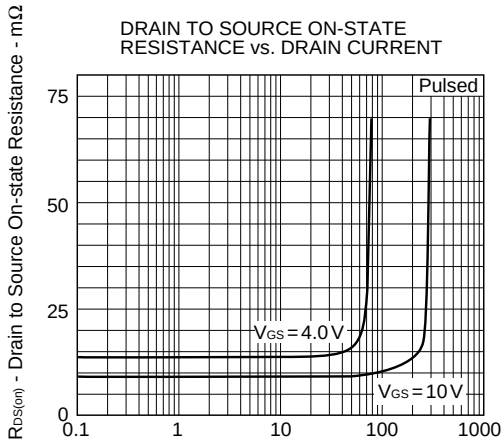
FORWARD TRANSFER ADMITTANCE vs.
DRAIN CURRENT



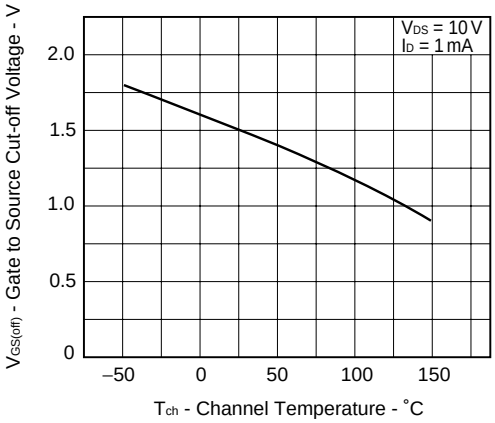
DRAIN TO SOURCE ON-STATE RESISTANCE vs.
GATE TO SOURCE VOLTAGE



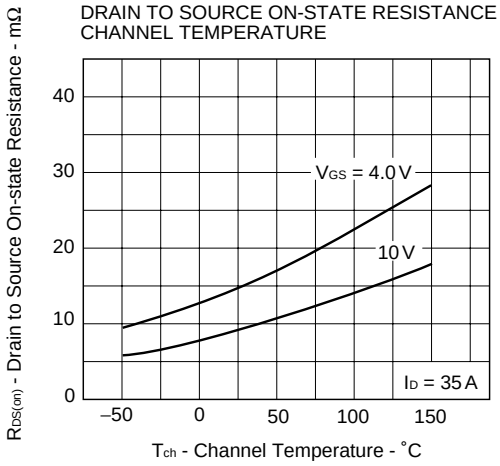
DRAIN TO SOURCE ON-STATE
RESISTANCE vs. DRAIN CURRENT



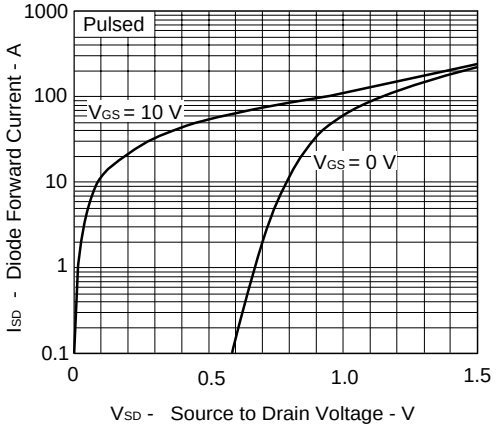
GATE TO SOURCE CUT-OFF VOLTAGE vs.
CHANNEL TEMPERATURE



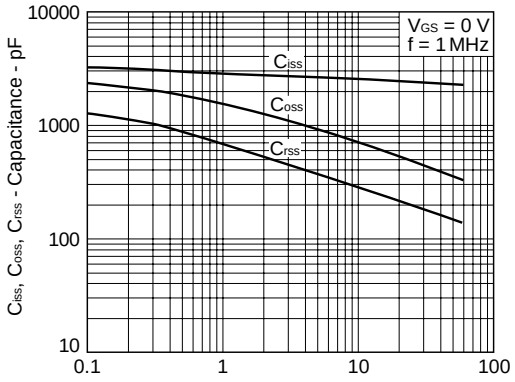
DRAIN TO SOURCE ON-STATE RESISTANCE vs. CHANNEL TEMPERATURE



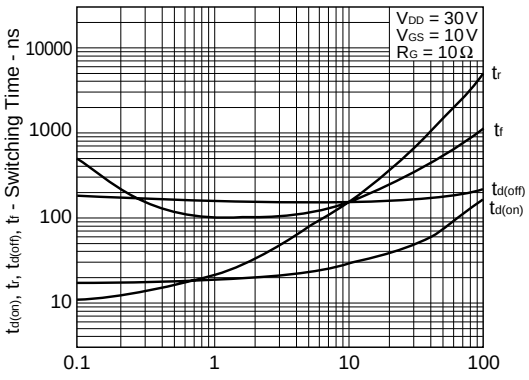
SOURCE TO DRAIN DIODE FORWARD VOLTAGE



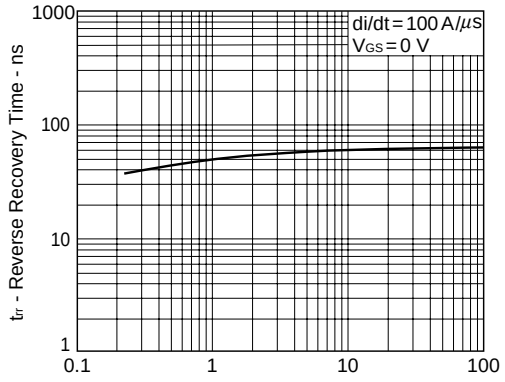
CAPACITANCE vs. DRAIN TO SOURCE VOLTAGE



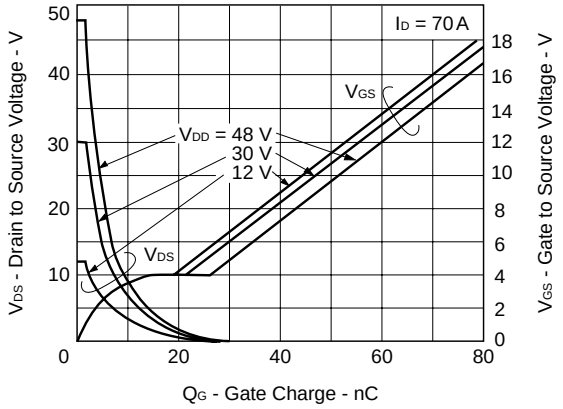
SWITCHING CHARACTERISTICS



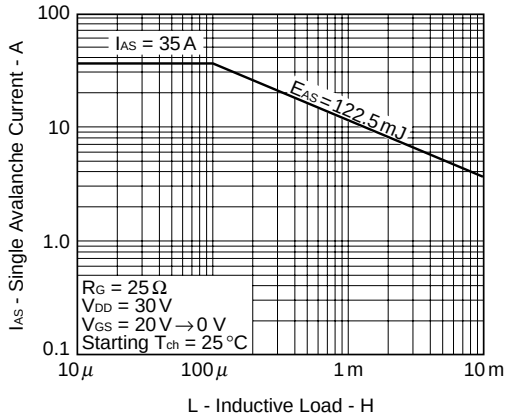
REVERSE RECOVERY TIME vs. DRAIN CURRENT



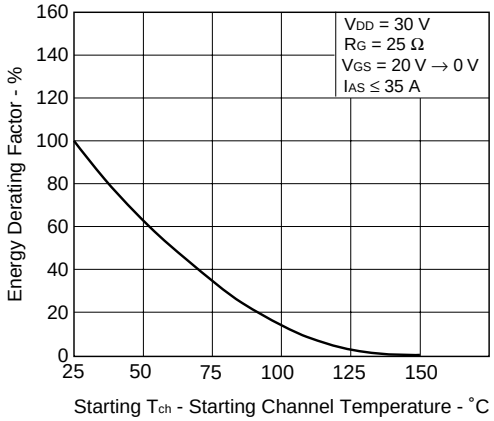
DYNAMIC INPUT/OUTPUT CHARACTERISTICS



SINGLE AVALANCHE CURRENT vs.
INDUCTIVE LOAD

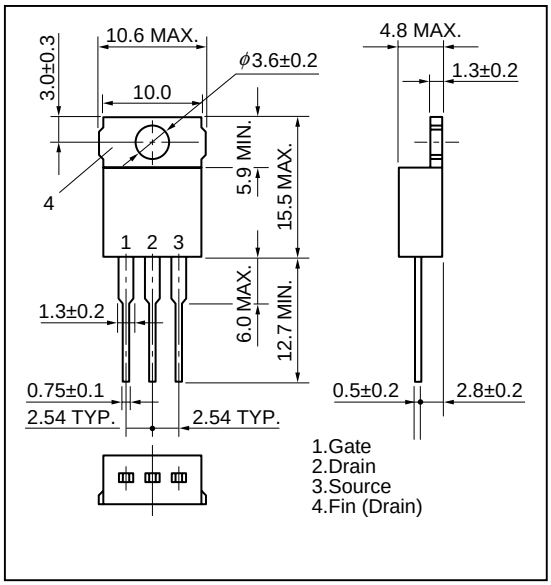


SINGLE AVALANCHE ENERGY
DERATING FACTOR

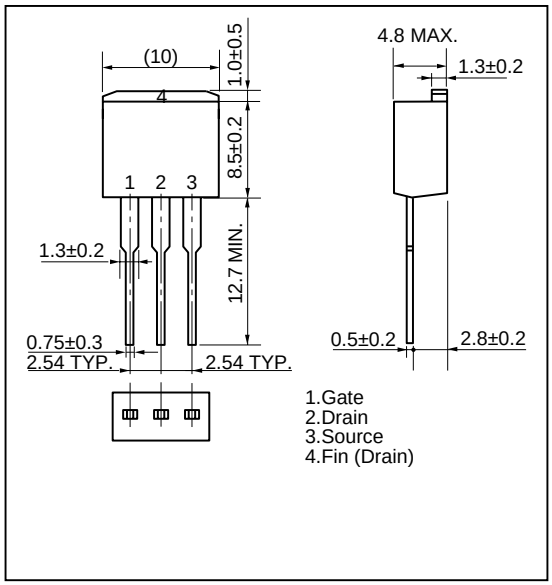


PACKAGE DRAWINGS (Unit : mm)

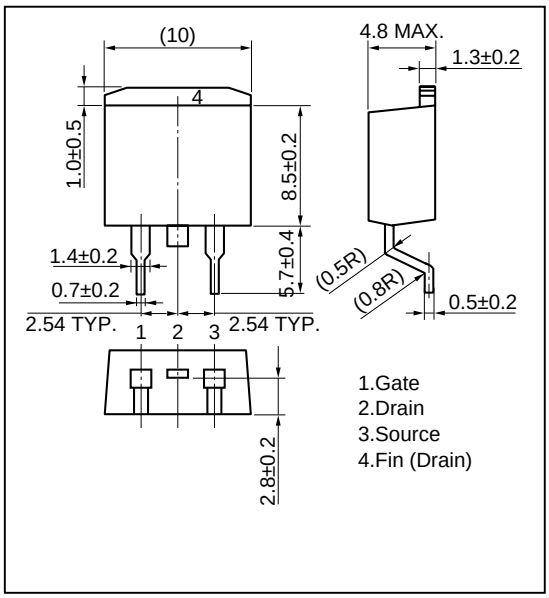
1)TO-220AB (MP-25)



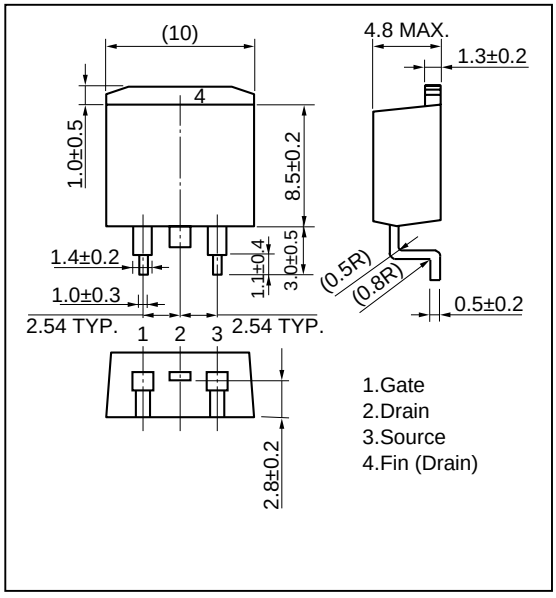
2)TO-262 (MP-25 Fin Cut)



3)TO-263 (MP-25ZJ)

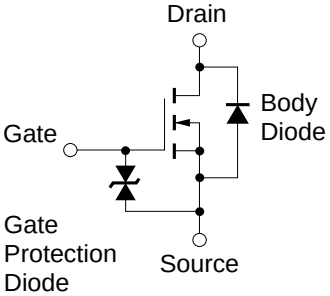


★ 4)TO-220SMD (MP-25Z) Note



Note This package is produced only in Japan.

EQUIVALENT CIRCUIT



Remark The diode connected between the gate and source of the transistor serves as a protector against ESD. When this device actually used, an additional protection circuit is externally required if a voltage exceeding the rated voltage may be applied to this device.

- **The information in this document is current as of April, 2001. The information is subject to change without notice. For actual design-in, refer to the latest publications of NEC's data sheets or data books, etc., for the most up-to-date specifications of NEC semiconductor products. Not all products and/or types are available in every country. Please check with an NEC sales representative for availability and additional information.**
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M8E 00.4